imall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832 Email & Skype: info@chipsmall.com Web: www.chipsmall.com Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



MAGNETIC FIELD SENSOR

DESCRIPTION

The ZMY20 is an extremely sensitive magnetic sensor employing the magneto-resistive effect of thin film permalloy. It allows the measurement of magnetic fields or the detection of magnetic parts. The highly sensitive and small size magnetoresistive sensors consist of a chip covered with thin film permalloy stripes. These stripes form a Wheatstone bridge, whose output voltage is proportional to the magnetic field component Hy. A perpendicular field Hx is necessary to stabilize sensor operation. This can be done by using a small permanent magnet.

FEATURES

- Output voltage proportional to magnetic field Hy
- Adjustment of sensitivity and suppression of hysteresis by the auxiliary magnetic field Hx
- Magnetic fields vertical to the chip level are not effective

APPLICATIONS

- Linear position sensors for process control, door interlocks, proximity detectors, machine tool sensing
- · Scalar measurement for compassing
- Automotive door switches, engine position & speed sensing
- · Metering of fluids by sensing rotation of impeller
- Traffic counting & vehicle-type sensing

ORDERING INFORMATION

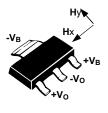
DEVICE	REEL SIZE	TAPE WIDTH	QUANTITY PER REEL	
ZMY20TA	7″	12mm	1000 units	
ZMY20TC	13″	12mm	4000 units	

Measurement of current in a conductor without connection

DEVICE MARKING

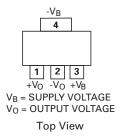
• ZMY20

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SOT223S







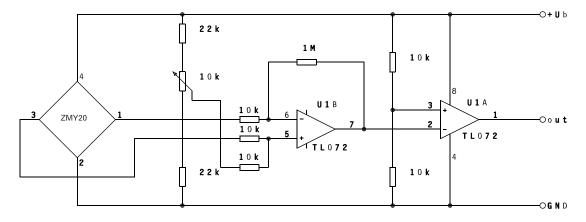
ABSOLUTE MAXIMUM RATINGS.

PARAMETER	SYMBOL	LIMIT	UNIT
Supply Voltage	V _B	12	V
Total power dissipation	P _{TOT}	120	mW
Operating Temperature Range	T _{amb}	-40 to +150	°C
Storage Temperature Range	T _{stg}	-65 to +150	°C

ELECTRICAL CHARACTERISTICS.(at T_{amb} =25°C and H_X =3 kA/m unless otherwise stated)

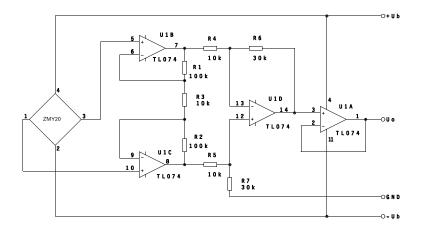
PARAMETER	SYMBOL	MIN	ТҮР	MAX	UNIT	TEST CONDITIONS
Bridge resistance	R _{br}	1.2	1.7	2.2	kΩ	
Output voltage range	V _O /V _B	16	20	24	mV/V	
Open circuit sensitivity	S	3.7	4.7	5.7	(mV/V)/ (kA/m)	No disturbing field H _d allowed
Hysteresis of output voltage	V _{OH} /V _B	-	-	50	μV/V	Hy≤ 2kA/m
Offset Voltage	V _{off} /V _B	-1.0	-	+1.0	mV/V	
Operating Frequency	f _{max}	0	-	1	MHz	
Temp. Coeff. of offset voltage	TCV _{off}	-3	-	+3	(µV/V)/K	T _{amb} = -25 to +125°C
Temp. Coeff. Of bridge resistance	TCR _{br}	0.25	0.3	0.35	%/K	T _{amb} = -25 to +125°C
Temp. Coeff. of open circuit sensitivity V _B =5V	TCSV	-0.25	-0.3	-0.35	%/K	T_{amb} = -25 to +125°C
Temp. Coeff. of open circuit sensitivity I _B =3mA	TCSI	-	-0.1	-	%/K	T_{amb} = -25 to +125°C





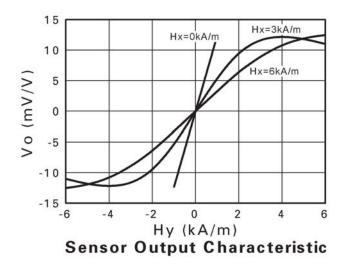
Application 1 (digital output)

Application 2 (analog output)

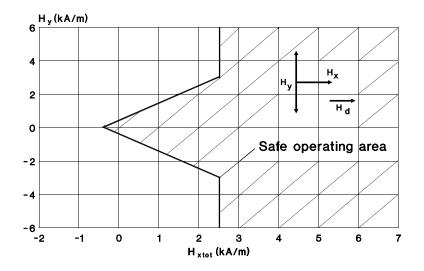




Sensor output characteristic VO=f(Hy); Hx-parameter Vb=const; Tamb=25°C

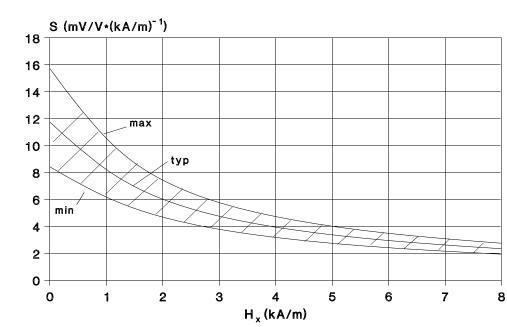


Safe operating area $H_{xtot}=H_x + H_d$; $T_{amb}=25^{\circ}C$; (H_d =disturbing field)



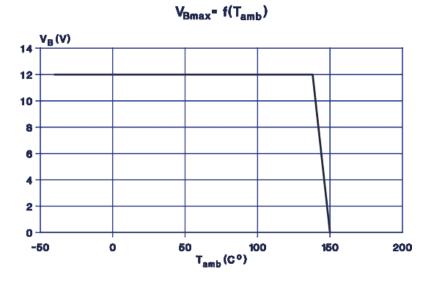
The sensor has to be reset after leaving the safe operating area by an auxiliary field of $H_X=3kA/m$





 $\begin{array}{l} Sensor \ sensitivity \ characteristic \\ S=f(H_X) \\ V_b=const; \ T_{amb}=25^\circ C \end{array}$

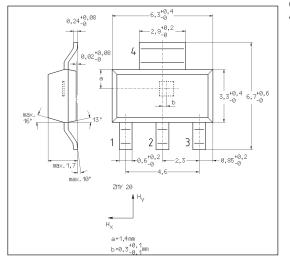
Supply voltage (maximum) derating curve VBmax=f(Tamb)



Device mounted on 40 x 40 mm² board (copper area 600mm²)



PACKAGE OUTLINE



CONTROLLING DIMENSIONS IN MILLIMETRES APPROX CONVERSIONS INCHES.



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or

2. support or sustain life and whose failure to perform when properly used in accordance with instructions

for use provided in the labeling can be reasonably expected to result in significant injury to the user.

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Semiconductor devices are susceptible to damage by ESD. Suitable precautions should be taken when handling and transporting devices. The possible damage to devices depends on the circumstances of the handling and transporting, and the nature of the device. The extent of damage can vary from immediate functional or parametric malfunction to degradation of function or performance in use over time. Devices suspected of being affected should be replaced.

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"Preview"Future device intended for production at some point. Samples may be available

"Active"Product status recommended for new designs

"Last time buy (LTB)"Device will be discontinued and last time buy period and delivery is in effect

"Not recommended for new designs"Device is still in production to support existing designs and production

"Obsolete"Production has been discontinued

Datasheet status key:

"Draft version"This term denotes a very early datasheet version and contains highly provisional

information, which may change in any manner without notice.

"Provisional version"This term denotes a pre-release datasheet. It provides a clear indication of anticipated performance. However, changes to the test conditions and specifications may occur, at any time and without notice.

"Issue" This term denotes an issued datasheet containing finalized specifications. However, changes to specifications may occur, at any time and without notice.



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Europe

Zetex GmbH Kustermann-Park Balanstraße 59 D-81541 München Germany Telefon: (49) 89 45 49 49 0 Fax: (49) 89 45 49 49 49 europe.sales@zetex.com

Zetex Inc 700 Veterans Memorial Hwy Hauppauge, NY 11788 USA Telephone: (1) 631 360 2222

Americas

Telephone: (1) 631 360 2222 Fax: (1) 631 360 8222 usa.sales@zetex.com



Asia Pacific

Zetex (Asia) Ltd 3701-04 Metroplaza Tower 1 Hing Fong Road, Kwai Fong Hong Kong

Telephone: (852) 26100 611 Fax: (852) 24250 494 asia.sales@zetex.com

Corporate Headquarters

Zetex Semiconductors plc Zetex Technology Park Chadderton, Oldham, OL9 9LL United Kingdom

Telephone (44) 161 622 4444 Fax: (44) 161 622 4446 hq@zetex.com